

IN THE SPECIFICATION

The paragraph beginning at page 9, line 10 has been amended as follows:

The substrate TS has one or more dielectric layers DS with metallized ~~levels~~ layers ME arranged on, underneath and (in cases with several layers) between the dielectric layers. The metallization ~~levels~~ layers ME are connected with each other through interlayer connections DK, and also with the component structures arranged on the upper side of the substrate (such as resonators or filters and the plate of the end device) through interlayer connections DK, connection lines, and electric connectors. The metallization levels ME can comprise, at least partially, adapter elements, bandpass filter TX-BP and RX-Bp as well as other circuit elements (e.g., inductances, capacitances, line sections).